

DERWENT-ACC-NO: 1991-325441
DERWENT-WEEK: 199144
COPYRIGHT 1999 DERWENT INFORMATION LTD

TITLE: Housing for electronic power components for fixing
to heat sink - has
components fixed to dielectric sheet which is pushed
against heat sink by
moulded cover

INVENTOR: BOUGEARD, J Y; CAULLET, A ; DUPONT, J ; HOUARD, P

PATENT-ASSIGNEE: MCB[MCBMN], MCB SA[MCBSN]

PRIORITY-DATA: 1990FR-0004395 (April 5, 1990)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE
PAGES	MAIN-IPC	
WO 9115873 A	October 17, 1991	N/A
000	N/A	
EP 481035 A	April 22, 1992	F
022	N/A	
FR 2660826 A	October 11, 1991	N/A
000	N/A	

DESIGNATED-STATES: CA FI JP US AT BE CH DE DK GB GR IT NL
SE AT BE CH DE DK GB G
R IT LI NL SE

CITED-DOCUMENTS: DE 2728564; EP 205746 ; FR 2503526 ; FR
2535898

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO
APPL-DATE		
EP 481035A	N/A	1991EP-0907586
March 20, 1991		
EP 481035A	Based on	WO 9115873
N/A		

INT-CL_(IPC): H01L025/07; H05K005/02 ; H05K007/20

ABSTRACTED-PUB-NO: WO 9115873A

BASIC-ABSTRACT: Electric power components (6) are firmly

fixed to the inner
surface (2a) of a dielectric sheet (2) of a good thermal
conductor. A moulded
cover (1), enclosing its inner surface (2a), pushes the
outer, exposed surface
onto the plate of a heat sink.

The cover has slots through which lugs (3) enter in one
direction (3a) and are
displaced (3d) to be clamped in a boss (1f) so that the
feet make electrical
contact with the component. The free volume inside the
cover is filled by an
adhering fluid which sets to a cohesive, supple, relatively
incompressible
dielectric.

ADVANTAGE - Large power-to-volume ratio, housing protects
components, small
number of parts, reduced number of manufacturing
operations.

CHOSEN-DRAWING: Dwg.7/9

TITLE-TERMS:

HOUSING ELECTRONIC POWER COMPONENT FIX HEAT SINK COMPONENT
FIX DIELECTRIC SHEET
PUSH HEAT SINK MOULD COVER

DERWENT-CLASS: U11 V04

EPI-CODES: U11-D01B3; U11-D02D; V04-T03A;

SECONDARY-ACC-NO:

Non-CPI Secondary Accession Numbers: N1991-249463

L Number	Hits	Search Text	DB	Time stamp
-	392084	semiconductor integrated adj circuit ic	USPAT; US-PGPUB	2002/06/04 20:25
-	51292	press! adj fit\$	USPAT; US-PGPUB	2002/06/04 20:25
-	568274	terminal	USPAT; US-PGPUB	2002/06/04 20:26
-	873	(press! adj fit\$) near3 terminal	USPAT; US-PGPUB	2002/06/04 20:26
-	92	((press! adj fit\$) near3 terminal) and (semiconductor integrated adj circuit ic)	USPAT; US-PGPUB	2002/06/04 20:26
-	2540793	@ad<19970509 @rlad<19970509	USPAT; US-PGPUB	2002/06/04 20:26
-	55	((press! adj fit\$) near3 terminal) and (semiconductor integrated adj circuit ic)) and (@ad<19970509 @rlad<19970509)	USPAT; US-PGPUB	2002/06/05 12:01
-	92293	encapsulat\$	USPAT; US-PGPUB	2002/06/04 20:36
-	14	(press! adj fit\$) near3 encapsulat\$	USPAT; US-PGPUB	2002/06/04 20:37
-	630	mold\$ near3 (press! adj fit\$)	USPAT; US-PGPUB	2002/06/04 20:38
-	67	(mold\$ near3 (press! adj fit\$)) and (semiconductor integrated adj circuit ic)	USPAT; US-PGPUB	2002/06/04 20:38
-	57	((mold\$ near3 (press! adj fit\$)) and (semiconductor integrated adj circuit ic)) and (@ad<19970509 @rlad<19970509)	USPAT; US-PGPUB	2002/06/04 20:38
-	57	((mold\$ near3 (press! adj fit\$)) and (semiconductor integrated adj circuit ic)) and (@ad<19970509 @rlad<19970509)) not (((press! adj fit\$) near3 terminal) and (semiconductor integrated adj circuit ic)) and (@ad<19970509 @rlad<19970509))	USPAT; US-PGPUB	2002/06/04 20:38
-	1	("5143757").PN.	USPAT; US-PGPUB	2002/06/05 12:02
-	1	("5243757").PN.	USPAT; US-PGPUB	2002/06/05 12:31
-	0	("7153906").PN.	JPO; DERWENT	2002/06/05 12:31
-	0	"07153906"	USPAT; US-PGPUB	2002/06/05 12:31
-	2	"07153906"	JPO; DERWENT	2002/06/05 16:11
-	1	1995-249779.NRAN.	DERWENT	2002/06/05 12:58
-	1	1995-249779.NRAN.	DERWENT	2002/06/05 12:59
-	0	7153906.URPN.	USPAT	2002/06/05 13:00
-	0	7153906.URPN.	USPAT	2002/06/05 13:00

-	3	"2660826"	EPO; JPO; DERWENT	2002/06/05 13:01
-	1	1991-325441.NRAN.	DERWENT	2002/06/05 13:01
-	1	1991-325441.NRAN.	DERWENT	2002/06/05 13:10